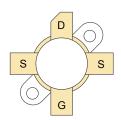


50V, 400W, 150MHz

RF POWER VERTICAL MOSFET

The VRF2944 is a gold-metallized silicon n-channel RF power transistor designed for broadband commercial and military applications requiring high power and gain without compromising reliability, ruggedness, or inter-modulation distortion.



FEATURES

- Improved Ruggedness $V_{(BR)DSS} = 170V$
- · 400W with 22dB Typ. Gain @ 30MHz, 50V
- · Excellent Stability & Low IMD
- Common Source Configuration
- · Available in Matched Pairs

- 3:1 Load VSWR Capability at Specified Operating Conditions
- Nitride Passivated
- · Refractory Gold Metallization
- Higher Power Version of VRF2933
- Thermally Enhanced Package
- RoHS Compliant



Maximum Ratings All Ratings: T_c =25°C unless otherwise specified

Symbol	Parameter	VRF2933(MP)	Unit
V _{DSS}	Drain-Source Voltage	170	V
I _D	Continuous Drain Current @ T _C = 25°C	50	Α
V_{gs}	Gate-Source Voltage	±40	V
P_{D}	Total Device dissipation @ T _C = 25°C	795	W
T _{STG}	Storage Temperature Range	-65 to 150	°C
T _J	Operating Junction Temperature Max	200	

Static Electrical Characteristics

Symbol	Parameter	Min	Тур	Max	Unit
$V_{(BR)DSS}$	Drain-Source Breakdown Voltage (V _{GS} = 0V, I _D = 100mA)	170	180		V
V _{DS(ON)}	On State Drain Voltage (I _{D(ON)} = 25A, V _{GS} = 10V)		1.7	2.1	l v
I _{DSS}	Zero Gate Voltage Drain Current (V _{DS} = 100V, V _{GS} = 0V)			2.0	mA
I _{GSS}	Gate-Source Leakage Current (V _{DS} = ±20V, V _{DS} = 0V)			2.0	μΑ
g_{fs}	Forward Transconductance (V _{DS} = 10V, I _D = 20A)	10			mhos
V _{GS(TH)}	Gate Threshold Voltage (V _{DS} = 10V, I _D = 100mA)	2.9	3.6	4.4	V

Thermal Characteristics

Symb	ool	Characteristic	Min	Тур	Max	Unit
$R_{\theta J0}$	2	Junction to Case Thermal Resistance			0.22	°C/W

CAUTION: These Devices are Sensitive to Electrostatic Discharge. Proper Handling Procedures Should Be Followed.

Dynamic Characteristics

- \/	RF	20	11	/ ПЛ	
v	\mathbf{I}	4 3		(IVI	

Symbol	Parameter	Test Conditions	Min	Тур	Max	Unit
C _{ISS}	Input Capacitance	V _{GS} = 0V		1050		
C _{oss}	Output Capacitance	V _{DS} = 50V		520		pF
C _{rss}	Reverse Transfer Capacitance	f = 1MHz		62		

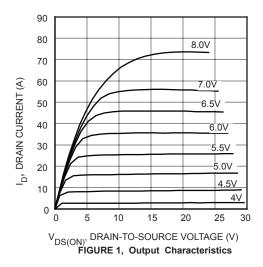
Functional Characteristics

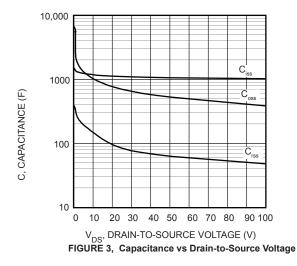
Symbol	Parameter		Тур	Max	Unit
G_{PS}	$f_1 = 30MHz, V_{DD} = 50V, I_{DQ} = 250mA, P_{out} = 400W$	23	25		dB
$\eta_{\scriptscriptstyle D}$	$f_1 = 30MHz, V_{DD} = 50V, I_{DQ} = 250mA, P_{out} = 400W$		50		%
Ψ	$f_1 = 30MHz$, $V_{DD} = 50V$, $I_{DQ} = 250mA$, $P_{out} = 400W$ 3:1 VSWR - All Phase Angles	No Degradation in Output Pow		Power	

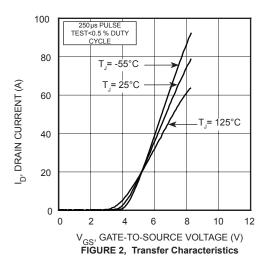
^{1.} To MIL-STD-1311 Version A, test method 2204B, Two Tone, Reference Each Tone

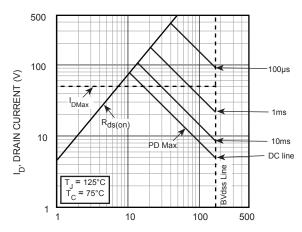
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Typical Performance Curves

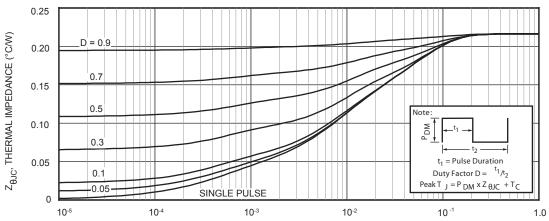








 V_{DS} , DRAIN-TO-SOURCE VOLTAGE (V) FIGURE 4, Forward Safe Operating Area



RECTANGULAR PULSE DURATION (seconds)
Figure 5. Maximum Effective Transient Thermal Impedance Junction-to-Case vs Pulse Duration

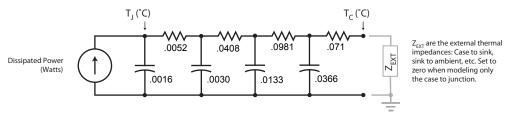
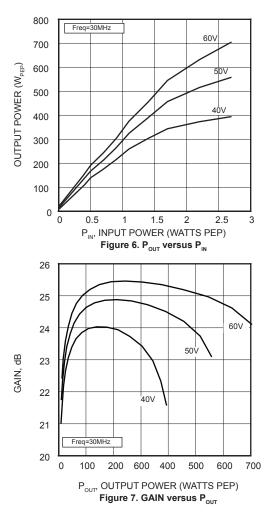


FIGURE 5b, TRANSIENT THERMAL IMPEDANCE MODEL



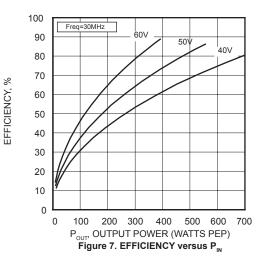
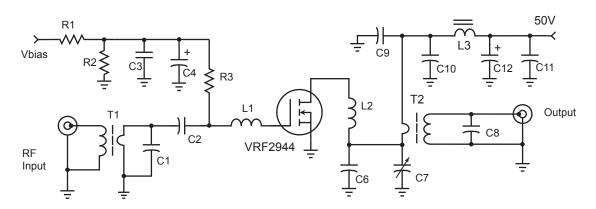


Table 1 - Typical Class AB Large Signal Input - Output Impedance

Freq. (MHz)	Z _{in}	Z _{out}	
30	4.5 - j 2.5	2.15 - j 2.71	

 I_{dq} = 100mA Z_{OL} - Conjugate of optimum load for 400 Watts output at V_{dd} =150V

30 MHz Test Circuit

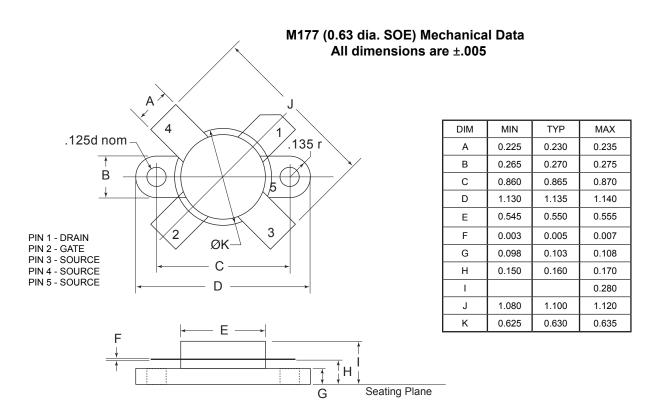


C1 1200pF ATC100B ceramic C2, C3 0.1uF 100V 1206 SMT C9-C11 .047uF NPO 100V 1218 SMT C6 180 pF metal clad mica C7 ARCO 465 mica trimmer C8 100 pF ATC 100E ceramic C4, C12 10uF 100V Electrolytic L1 25 nH - 2t #18 0.2"d .2"l L2 26 nH - 1.5t #12 0.31"d2 L3 2t #16 on 2x 267300081 .5" bead R1-R2 1k Ω 1/4W R3 100 Ω 1W T1 16:1 transforner 4t #24 teflon on RF Parts Co. T1/2 transformer core T2 9:1 transformer 3t 2-ply #16 teflon on RF Parts Co. T1 transformer core

Adding MP at the end of P/N specifies a matched pair where $V_{GS(TH)}$ is matched between the two parts. V_{TH} values are marked on the devices per the following table.

Code	Vth Range	Code 2	Vth Range
Α	2.900 - 2.975	М	3.650 - 3.725
В	2.975 - 3.050	N	3.725 - 3.800
С	3.050 - 3.125	Р	3.800 - 3.875
D	3.125 - 3.200	R	3.875 - 3.950
E	3.200 - 3.275	S	3.950 - 4.025
F	3.275 - 3.350	Т	4.025 - 4.100
G	3.350 - 3.425	W	4.100 - 4.175
Н	3.425 - 3.500	Х	4.175 - 4.250
J	3.500 - 3.575	Υ	4.250 - 4.325
K	3.575 - 3.650	Z	4.325 - 4.400

 $V_{_{TH}}$ values are based on Microsemi measurements at datasheet conditions with an accuracy of 1.0%.



HAZARDOUS MATERIAL WARNING: The ceramic portion of the device below the lead plane is beryllium oxide. Beryllium oxide dust is highly toxic when inhaled. Care must be taken during handling and mounting to avoid damage to this area. These devices must never be thrown away with general industrial or domestic waste. BeO substrate weight: 0.703g. Percentage of total module weight which is BeO: 9%.

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